

#### **Presentation Disclaimer**

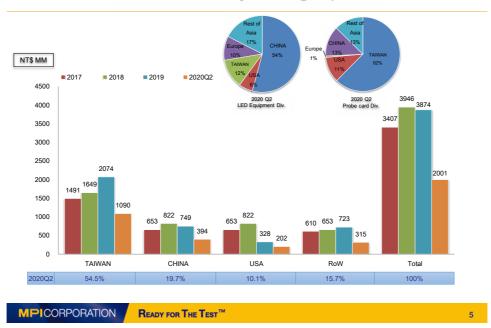
The information herein contains forward-looking statements. We have based these forward-looking statements on our current expectations and projections about future events. Although we believe that these expectations and projections are reasonable, such forward-looking statements are inherently subject to risks, uncertainties and assumptions about us, including, among other things: the intensely competitive Semi-conductor, and LED industries and markets; Cyclical nature of the semiconductor industry; Risks associated with global business activities; General economic and political conditions. All financial figures discussed herein are prepared pursuant to IFRS. All audited figures will be publicly announced upon the completion of our audited process.

# Company at a Glance

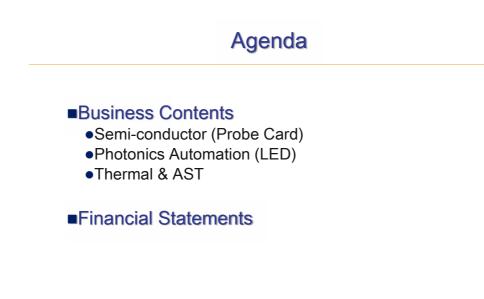


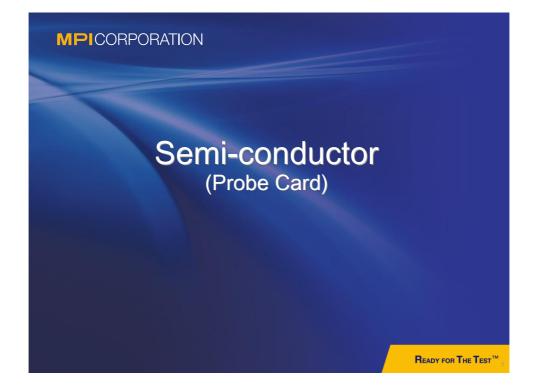
#### **Business Portfolio**



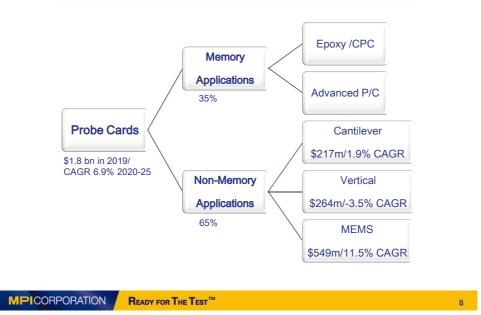


#### Net Sales by Geographic





## **Global Probe Card Market Update**



# Top 10 Probe Card Vendors (2014-2019)

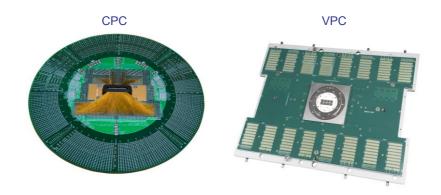
(Rank)		2014	2015	2016	2017	2018	2019
FormFactor, Inc.	USA	1	1	1	1	1	1
Micronics Japan Co., Ltd.	Japan	2	2	2	2	3	3
Technoprobe	Italy	3	3	3	3	2	2
Japan Electronic Materials	Japan	4	4	4	4	4	4
MPI Corporation	Taiwan	5	5	5	5	5	5
SV TCL	Singapore	9	7	6	6	6	6
Microfriend	Korea	8	10	7	7	10	10
Korea Instrument	Korea	6	9	8	8	7	8
Cascade Microtech	USA	7	6	9	-	-	-
FEINMETALL	Germany	11	11	10	11	12	11

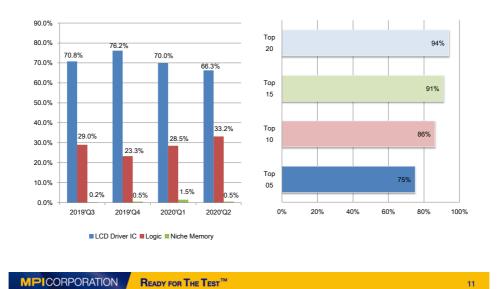
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#### CPC & VPC





## Product Mix of CPC (Cantilever)

## **CPC Pin-Shipment**

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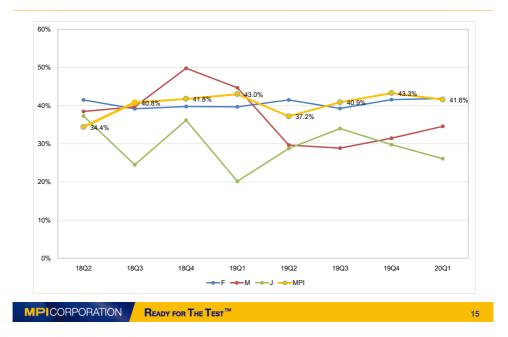




## **VPC Pin-Shipment**

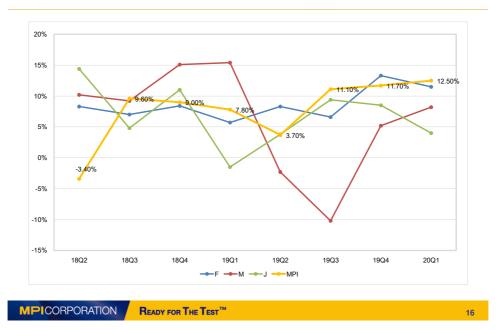
#### CPC and VPC Yearly Status

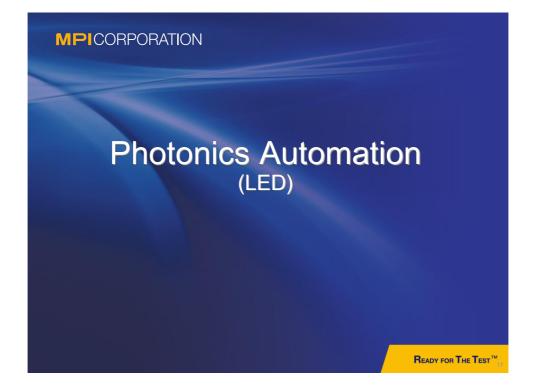




#### **Gross Margin Between Global Peers**

## **Operating Margin Between Global Peers**





## Photonics Automation (PA) Overview





#### Main Product Line



Package Level Chip Scale Package (CSP) Foil to Foll (FTF) Inspection System

Chip after dicing Chip after sorting



Package Probing

Panel Bottom probing Single package



Package Testing From low to high power







LED Package Probing

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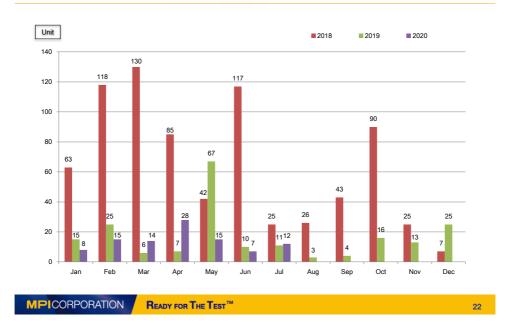
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#### 855 699 195 P,9000 P7602F P80C4 NEW A2000P A3000 NEW M76FP M76V M60D MPICORPORATION READY FOR THE TEST<sup>™</sup> 21

# Wafer Technology Migration

# 2020 Shipment





#### Thermal



- Addressable Market Size: roughly USD\$30m
- Applied Industries: Telecom / Automotive/Industrial, industrial and semi industries

http://www.mpi-thermal.com/media/

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# AST

- Market size: roughly USD\$400m
- Industry: Foundry/IC design houses' engineering stage process







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# **Balance Sheet Highlight**

	2Q 2	2Q 2019		
Cash and Cash Equivalents	1,190	14%	901	12%
Fixed Assets	3,442	41%	3,254	41%
Total Assets	8,330	100%	7,835	100%
LT Debt	309		24	
Shareholders' Equity	4,534	54%	4,103	52%
EBITDA	431		160	

\*EBITDA=operating income + depreciation & amortization expenses

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#### **Income Statement**

NT\$1,000	2020' 11	H	2019' 1H		
Net Sales	2,914,450	100%	2,528,962	100%	
Cost of Goods Sold	1,650,129	57%	1,558,715	62%	
Gross Profit	1,264,321	43%	970,247	38%	
Operating Expense	815,362	28%	833,778	33%	
Operating Income	448,959	15%	136,469	5%	
Investment Income & Others	-17,677		23,630		
Net Income (before tax)	365,598	13%	136,799	5%	
EPS	4.57		1.71		

